Replaced by Art. 19 Amendment

CLAIMS

1. A semiconductor device comprising: an insulating substrate having an obverse surface formed with a rectangular die pad made of a metal film and a pair of electrode terminals made of a metal film; a rectangular semiconductor chip bonded to an obverse surface of the die pad with a die bonding material; and a molded portion made of a synthetic resin for packaging the semiconductor chip;

wherein the rectangle of the die pad has a length and a width which are 0.50 to 1.50 times a length and a width of the rectangle of the semiconductor chip, respectively.

2. The semiconductor device according to claim 1, wherein the semiconductor chip comprises an LED chip, and wherein the molded portion is light-permeable.

3. The semiconductor device according to claim 1 or 2, wherein the die pad has a side surface integrally formed with a narrow extension projecting outward from the die pad.

4. The semiconductor device according to claim 1 or 2, wherein the die pad is formed with a recess of a size insufficient to receive the semiconductor chip.

5. The semiconductor device according to claim 1 or 2, wherein the die pad has a side surface integrally formed with a narrow extension projecting outward from the die pad, and wherein the

die pad is formed with a recess of a size insufficient to receive the semiconductor chip.

6. A semiconductor device comprising: an insulating substrate having an obverse surface formed with a die pad made of a metal film and a pair of electrode terminals made of a metal film; a semiconductor chip which is square or generally square as viewed in plan and bonded to an obverse surface of the die pad with a die bonding material; and a molded portion made of a synthetic resin for packaging the semiconductor chip;

wherein the die pad is circular as viewed in plan and has a diameter which approximates a diagonal dimension of the semiconductor chip, and wherein a narrow patterned conductor made of a metal film is provided between the die pad and one of the electrode terminals to integrally connect the die pad and the electrode terminal to each other.

7. The semiconductor device according to claim 6, wherein the diameter of the die pad is 0.6 to 1.5 times the diagonal dimension of the semiconductor chip.

8. The semiconductor device according to claim 6 or 7, wherein the semiconductor chip comprises an LED chip, and wherein the molded portion is light-permeable.

9. The semiconductor device according to claim 6 or 7, wherein the paired electrode terminals are arranged, as viewed in plan, on a generally straight line with the die pad interposed

therebetween, the narrow patterned conductor being arranged to extend from a circumference of the die pad at a position deviating by 45 degrees from the line of the electrode terminals.

10. The semiconductor device according to claim 6 or 7, wherein the semiconductor chip comprises an LED chip, wherein the molded portion is light-permeable, and wherein the paired electrode terminals are arranged, as viewed in plan, on a generally straight line with the die pad interposed therebetween, the narrow patterned conductor being arranged to extend from a circumference of the die pad at a position deviating by 45 degrees from the line of the electrode terminals.

11. The semiconductor device according to claim 6 or 7, wherein the die pad is formed with a recess of a size insufficient to receive the semiconductor chip.

12. A semiconductor device comprising: a die pad made of a metal plate and a pair of electrode terminals made of a metal plate; a semiconductor chip which is square or generally square as viewed in plan and bonded to the die pad with a die bonding material; and a molded portion made of a synthetic resin for packaging the semiconductor chip;

wherein the die pad is circular as viewed in plan and has a diameter which approximates a diagonal dimension of the semiconductor chip, and wherein a narrow patterned conductor made of a metal plate is provided between the die pad and one of the electrode terminals to integrally connect the die pad

and the electrode terminal to each other.